

Marked-Up Version of Specification

In the Specification:

Amend the paragraphs at page 1, lines 9-19 of the application as follows:

"Electroless Metal Connection Structures and Methods," Eichelberger et al., [(Docket No. 1109.002),] Serial No. 09/501,200 [_____], co-filed herewith;

"Structure and Method for Temporarily Holding Integrated Circuit Chips in Accurate Alignment," [(Docket No. 1109.003),] Serial No. 09/501,176 [_____], co-filed herewith.

"Complaint, Solderable Input/Output Bump Structures," [(Docket No. 1109.004),] Serial No. 09/501,177 [_____], co-filed herewith; and